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PLATINUM/PALLADIUM/SILVER CONDUCTOR 9565

ESL 9565 is a mixed-bonded ternary conductor material for general purpose conductor applications, which exhibits excellent solder leach resistance, excellent silver migration resistance, good solder wetting, and excellent initial and aged adhesion. ESL 9565 is recommended for use as a resistor termination.

When used with 4905-C multilayer dielectric, ESL 9565 is well suited as a top layer conductor with excellent adhesion, bond retention, and leach resistance.

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C)	325±25 Pa•s
BONDING MECHANISM:	Mixed
SHELF LIFE: (25°C)	6 months

PROCESSING

SCREEN MESH/EMULSION:	325/25 µm
LEVELING TIME: (25°C)	5-10 minutes
DRYING AT 125°C:	10-15 minutes
FIRING RANGE:	850°C-930°C
OPTIMUM:	850°C
TIME AT PEAK:	10-12 minutes
RATE OF ASCENT/DESCENT:	60°C-100°C/minute
SUBSTRATE OF CALIBRATION:	96% alumina
THINNER:	ESL 401

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TYPICAL PROPERTIES

FIRED THICKNESS:	12.0±2.5 µm
RESISTIVITY:	24-36 mΩ/sq.
PRINTING RESOLUTION: (Line/Space)	250 µm x 250 µm
SOLDER WETTABILITY: (RMA flux, 5 sec. dip 62 Sn/36 Pb/2 Ag, 220°C±5°C)	Very good
SOLDER LEACH: (No. of 10 sec. dips to double resistance of 0.25 mm wide x 100 mm long conductor 62 Sn/36 Pb/2 Ag, 220°C±5°C)	5
ADHESION: (90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)	
Initial pull strength:	60 N
Aged 48 hours at 150°C:	49 N
ULTRASONIC WIRE BOND: (25 µm Al wire)	
Initial	5.5-5.8 grams
Aged 48 hours at 150°C:	3.6-4.0 grams
THERMOSONIC WIRE BOND: (25 µm Au wire)	
Initial:	4.0-4.8 grams